



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	TLE7258D	<b>Issued</b>	13. April 2021
<b>MA#</b>	MA005411133		
<b>Package</b>	PG-TSON-8-1	<b>Weight*</b>	26.83 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.828	3.09	3.09	30855	30855
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		110	
	non noble metal	zinc	7440-66-6	0.012	0.04		440	
	non noble metal	iron	7439-89-6	0.236	0.88		8799	
	non noble metal	copper	7440-50-8	9.586	35.73	36.66	357256	366605
wire	non noble metal	copper	7440-50-8	0.030	0.11	0.11	1131	1131
encapsulation	organic material	carbon black	1333-86-4	0.031	0.11		1143	
	plastics	epoxy resin	-	1.580	5.89		58885	
	inorganic material	silicondioxide	60676-86-0	13.729	51.17	57.17	511666	571694
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14244	14244
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1620	1620
glue	plastics	epoxy resin	-	0.093	0.35		3463	
	noble metal	silver	7440-22-4	0.279	1.04	1.39	10388	13851
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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